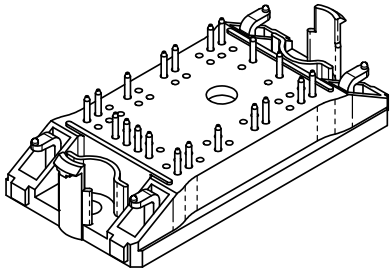
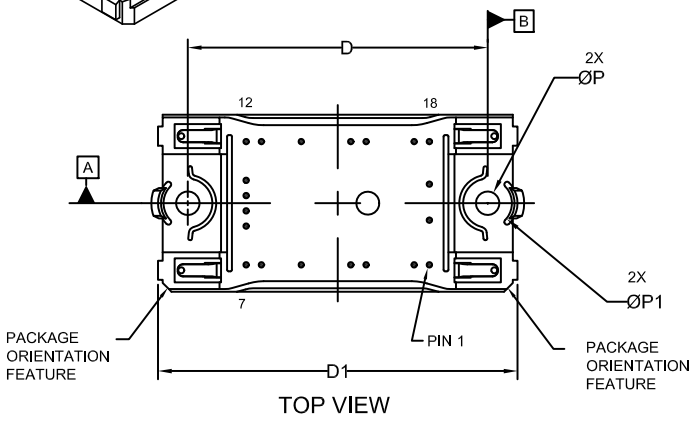
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

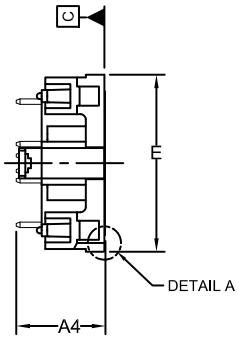
PIM20, 55x32.5 / Q0PACK
CASE 180AB
ISSUE D

DATE 21 NOV 2017



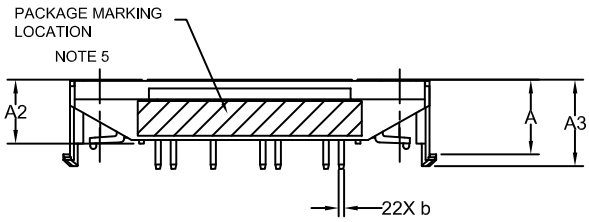


TOP VIEW

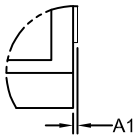


END VIEW

DIM	MILLIMETERS	
	MIN.	NOM.
A	13.50	13.90
A1	0.10	0.30
A2	11.50	11.90
A3	15.65	16.05
A4	16.35 REF	
b	0.95	1.05
D	54.80	55.20
D1	65.60	66.20
E	32.20	32.80
P	4.20	4.40
P1	8.90	9.10



SIDE VIEW



DETAIL A

NOTE 4

PIN	PIN POSITION		PIN	PIN POSITION	
	X	Y		X	Y
1	16.80	-11.30	11	-16.80	4.20
2	14.00	-11.30	12	-16.80	11.30
3	5.20	-11.30	13	-14.00	11.30
4	2.40	-11.30	14	-6.70	11.30
5	-6.70	-11.30	15	2.40	11.30
6	-14.00	-11.30	16	5.20	11.30
7	-16.80	-11.30	17	14.00	11.30
8	-16.80	-4.20	18	16.80	11.30
9	-16.80	-1.40	19	16.80	3.50
10	-16.80	1.40	20	16.80	-3.10

NOTES:

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 1.00 AND 3.00 FROM THE TERMINAL TIP.
4. POSITION OF THE CENTER OF THE TERMINALS IS DETERMINED FROM DATUM B THE CENTER OF DIMENSION D, X DIRECTION, AND FROM DATUM A, Y DIRECTION. POSITIONAL TOLERANCE, AS NOTED IN DRAWING, APPLIES TO EACH TERMINAL IN BOTH DIRECTIONS.
5. PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES.

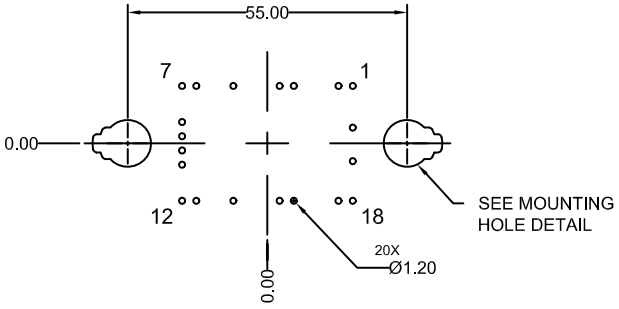
MOUNTING FOOTPRINT & MARKING DIAGRAM ON PAGE 2

PIM20, 55x32.5 / Q0PACK
CASE 180AB
ISSUE D

DATE 21 NOV 2017

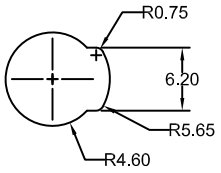
MOUNTING HOLE POSITION

	PIN POSITION			PIN POSITION	
PIN	X	Y	PIN	X	Y
1	16.80	11.30	11	-16.80	-4.20
2	14.00	11.30	12	-16.80	-11.30
3	5.20	11.30	13	-14.00	-11.30
4	2.40	11.30	14	-6.70	-11.30
5	-6.70	11.30	15	2.40	-11.30
6	-14.00	11.30	16	5.20	-11.30
7	-16.80	11.30	17	14.00	-11.30
8	-16.80	4.20	18	16.80	-11.30
9	-16.80	1.40	19	16.80	-3.50
10	-16.80	-1.40	20	16.80	3.10

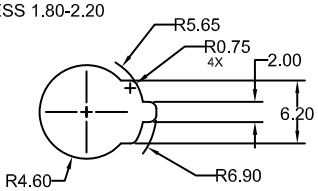


RECOMMENDED
MOUNTING PATTERN

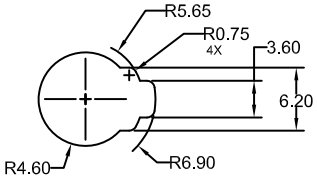
FOR PCB
THICKNESS 1.45-1.80



FOR PCB
THICKNESS 1.80-2.20

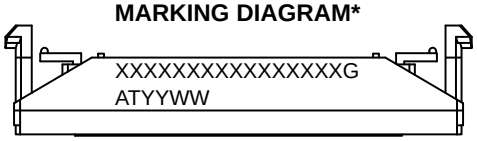


FOR PCB
THICKNESS 2.20-2.80



MOUNTING HOLE DETAIL

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
G = Pb−Free Package
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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STATUS:	**ON SEMICONDUCTOR STANDARD**		
NEW STANDARD:			
DESCRIPTION:	**PIM20 55X32.5 / Q0PACK (SOLDER PIN)**		**PAGE 2 OF 3**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY D. BUSHONG.	21 MAY 2015
A	MODIFIED TOP AND SIDE VIEWS AND CHANGED MARKING DIAGRAM. REQ. BY A. LAI.	01 MAR 2016
B	CHANGED DIMENSION TABLE CALLOUTS FROM MIN & NOM TO MIN & MAX. REQ. BY F. ESTRADA.	01 FEB 2017
C	UPDATED MARKING DIAGRAM CODE INFORMATION. REQ. BY A. LAI.	08 NOV 2017
D	REARRANGED DRAWING CONTENT. REQ. BY A. LAI.	21 NOV 2017